MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED

SS2150-MS THRU SS2200-MS

Product specification





Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability
 Classification Rating 94V-O

MECHANICAL DATA

- Case: SMA/DO-214AC, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Weight: 0.064 grams (approx.)

Reference News

DO-214AC/SMA	Schematic Diagram

Marking

SS2150-MS	SS2200-MS	
SS215	SS220	

Maximum Ratings and Electrical Characteristics T_A = 25 ℃ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

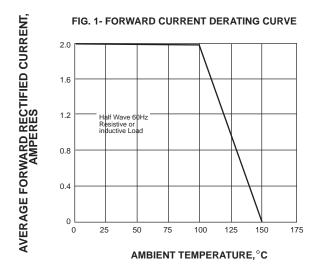
Characteristic	Symbol	SS2150-MS	SS2200-MS	Unit
Maximum repetitive peak reverse voltage	Vrrm	150	200	V
Maximum RMS voltage	VRMS	105	140	V
Maximum DC blocking voltage	VDC	150	200	V
Maximum average forward rectified current 0.375"(9.5mm) lead length(see fig.1)	l(AV)	2.0		А
Peak forward surge current				
8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	İFSM	50.0		А
Maximum instantaneous forward voltage at 2.0A	VF	0.85	0.95	V
Maximum DC reverse current T _A =25℃		0.2		
at rated DC blocking voltage T _A =100℃	lR	2.0		mA
Typical junction capacitance (NOTE 1)	Cu	80		pF
Typical thermal resistance (NOTE 2)	Reja	88		°C/W
Operating junction temperature range	TJ	-65 to +150		°C
Storage temperature range	Тѕтс	-65 to +1	150	°C

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

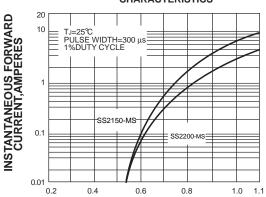
2.P.C.B. mounted with 0.2x0.2(5.0x5.0mm) copper pad areas



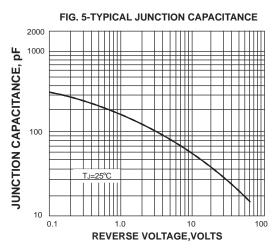
RATINGS AND CHARACTERISTIC CURVES SS2150-MS THRU SS2200-MS

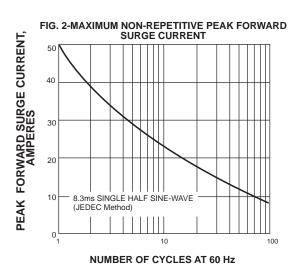


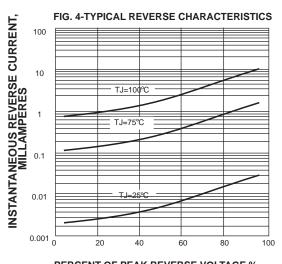




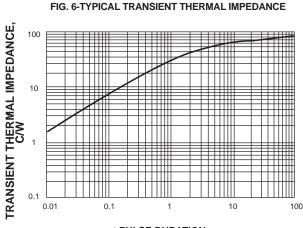
INSTANTANEOUS FORWARD VOLTAGE,







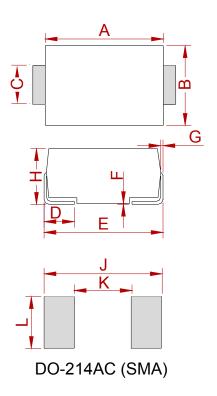
PERCENT OF PEAK REVERSE VOLTAGE,%



t,PULSE DURATION,sec.



PACKAGE MECHANICAL DATA



	Dimensions			
Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
Α	4.25	4.65	0.167	0.183
В	2.50	2.90	0.098	0.114
С	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
Е	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
Н	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
SS2150-MS THRU SS2200-MS	SMA(DO-214AC)	2000



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